

To: _____

Change Notice : Change of LED chip & Wire Bonding Method for Photocouplers

We appreciate your continuous patronage of our semiconductor products.

This letter is to inform you that Toshiba is planning the following changes in photocouplers which you are currently using. Your continuous support and patronage would be highly appreciated.

1. Affected product:

No	Change description	Affected products
1	Change of LED chip	Refer to the attachment
2	Change of Wire bonding method	

2. Description of the change:

No.	Change item	Description of the change
1	Change of LED chip	Toshiba will change LED chip mounted in our photocouplers to another LED chip that have been used in our different product type approximately hundreds of millions of pieces for the past 10 years. The chip shows equivalent characteristics before and after the change.
2	Change of Wire bonding method	The wire bonding method will be changed to the one for other product type with the same package to unify the bonding condition.

3. Reason of the change:

No.	Change item	Reason of the change
1	Change of LED chip	The current LED chip uses a material that has difficulties in substitutability and availability. Toshiba therefore change it to an alternative LED chip that does not use the material.
2	Change of Wire bonding method	The wire bonding method will be unified to the one for other product type using the same package and the same type of LED chip (e.g. TLP5212), aiming to simplify the process control.

4. Product characteristics and reliability:

The change would not impact to the product characteristics and reliability.
(See the explanatory material for the details).

5. Request from Toshiba:

- Regarding the above change, we plan to switch it from the production in December 2024, and we would like to receive your approval by November 13, 2024.
- It would be appreciated if you could verify the submitted evaluation results as soon as possible. If you have questions, please contact us through our sales representatives.

Sincerely yours,



H. Matsuo / Manager
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(Person in charge: K. Nishida, N. Miyoshi)